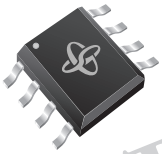
GENERAL SEMICONDUCTOR®

GF2208

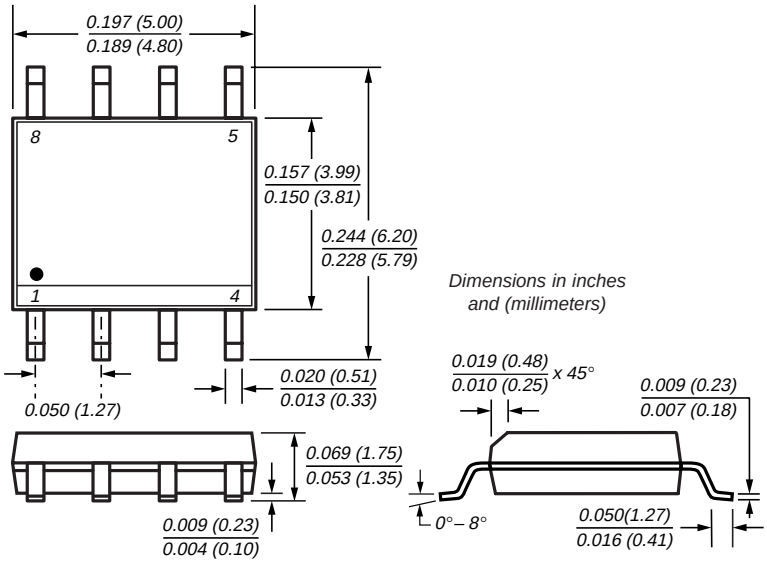
N-Channel Enhancement-Mode MOSFET

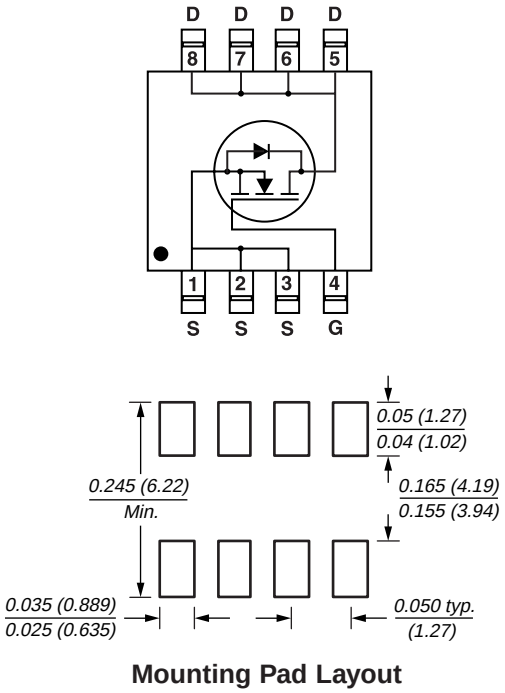
V_{DS} 30V **$R_{DS(ON)}$** 8mΩ **I_D** 13A



TRENCH GENFET®

SO-8





Mounting Pad Layout

Mechanical Data

Case: SO-8 molded plastic body

Terminals: Leads solderable per MIL-STD-750, Method 2026

High temperature soldering guaranteed: 250°C/10 seconds at terminals

Mounting Position: Any **Weight:** 0.5g

Features

- Advanced Trench Process Technology
- High Density Cell Design for Ultra Low On-Resistance
- Specially Designed for Low Voltage DC/DC Converters
- Fast Switching for High Efficiency

Maximum Ratings and Thermal Characteristics (T_A = 25°C unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	
Continuous Drain Current T_J = 150°C(1)	T_A = 25°C T_A = 70°C	I_D	13 10.5	A
Pulsed Drain Current		I_{DM}	±50	
Continuous Source Current (Diode Conduction)(1)		I_S	2.3	
Maximum Power Dissipation(1)	T_A = 25°C T_A = 70°C	P_D	2.5 1.6	W
Operating Junction and Storage Temperature Range		T_J, T_{stg}	–55 to 150	°C
Maximum Junction-to-Ambient(1) Thermal Resistance		$R_{\theta JA}$	50	°C/W

Notes: (1) Surface mounted on FR4 board, t ≤ 10 sec.

7/10/01

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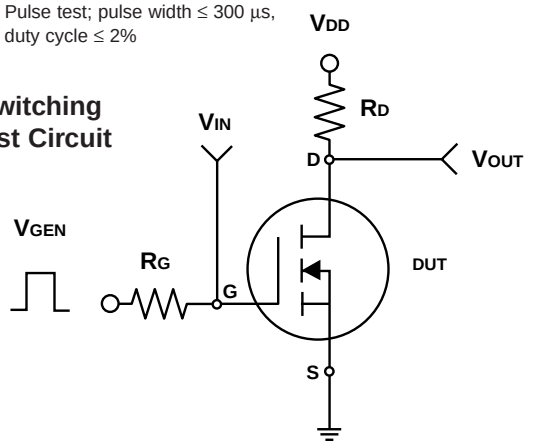
Electrical Characteristics (T_J = 25°C unless otherwise noted)

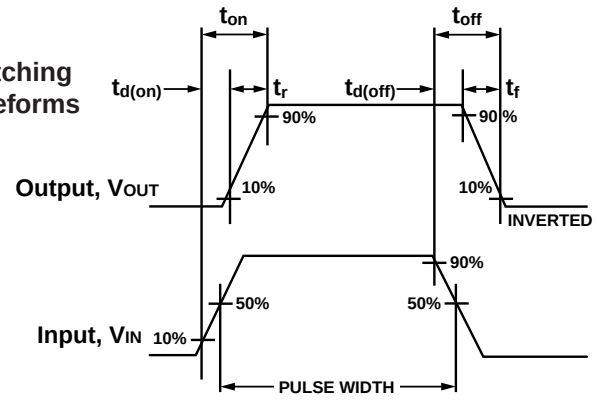
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS} = 0V, I_D = 250µA	30	–	–	V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250µA	1.0	–	3.0	V
Gate-Body Leakage	I_{GSS}	V_{DS} = 0V, V_{GS} = ±20V	–	–	±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 30V, V_{GS} = 0V	–	–	1	µA
		V_{DS}=30V, V_{GS}=0V, T_J=55°C	–	–	5	
On-State Drain Current[2]	$I_{D(on)}$	V_{DS} ≥ 5V, V_{GS} = 10V	30	–	–	A
Drain-Source On-State Resistance[2]	$R_{DS(on)}$	V_{GS} = 10V, I_D = 13A	–	6	8	mΩ
		V_{GS} = 4.5V, I_D = 11A	–	8.5	11	
Forward Transconductance[2]	g_{fs}	V_{DS} = 15V, I_D = 13A	–	50		S
Dynamic						
Total Gate Charge	Q_g	V_{DS} = 15V, V_{GS} = 4.5V, I_D = 13A	–	28	39	nC
		V_{DS} = 15V, V_{GS} = 10V, I_D = 13A	–	56	85	
Gate-Source Charge	Q_{gs}		–	7.5	–	
Gate-Drain Charge	Q_{gd}		–	10	–	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 15V, R_L = 15Ω, I_D ≈ 1A, V_{GEN} = 10V, R_G = 6Ω	–	9	14	ns
Rise Time	t_r		–	9	14	
Turn-Off Delay Time	$t_{d(off)}$		–	100	167	
Fall Time	t_f		–	31	62	
Input Capacitance	C_{iss}	V_{GS} = 0V, V_{DS} = 15V, f = 1.0MHz	–	3128	–	pF
Output Capacitance	C_{oss}		–	618	–	
Reverse Transfer Capacitance	C_{rss}		–	300	–	
Source-Drain Diode						
Diode Forward Voltage[2]	V_{SD}	I_S = 2.3A, V_{GS} = 0V	–	–	1.1	V
Source-Drain Reverse Recovery Time	t_{rr}	I_F = 2.3A, di/dt = 100A/µs	–	49	90	ns

Notes: (1) Surface mounted on FR4 board, t ≤ 10 sec.
(2) Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2%

Switching Test Circuit



Switching Waveforms



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Ratings and Characteristic Curves (TA = 25°C unless otherwise noted)

Fig. 1 – Output Characteristics

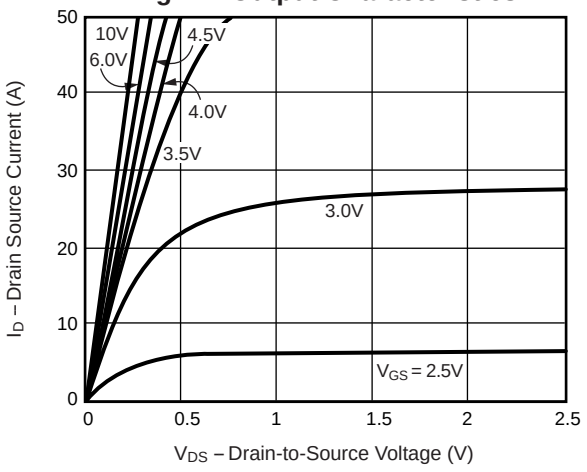


Fig. 2 – Transfer Characteristics

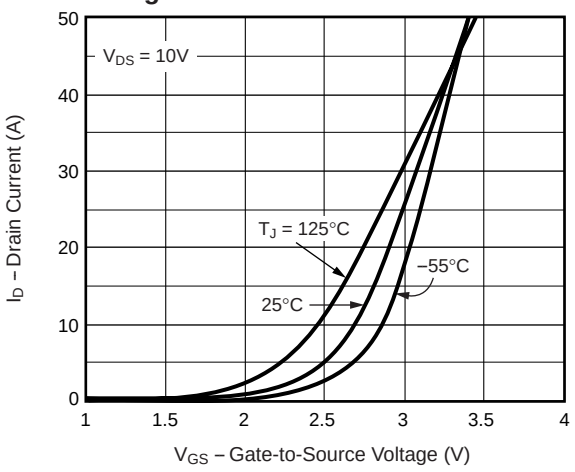


Fig. 3 – Threshold Voltage vs. Temperature

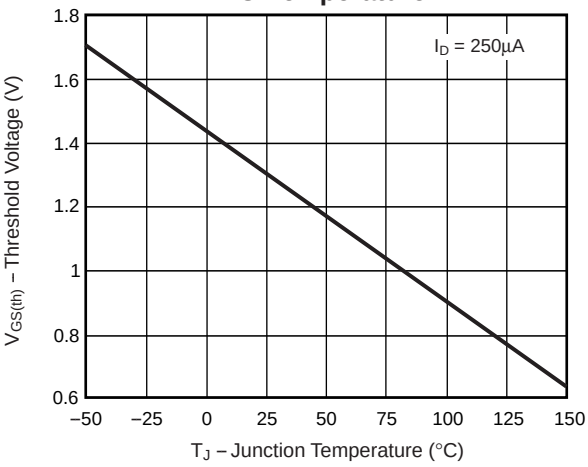


Fig. 4 – On-Resistance vs. Drain Current

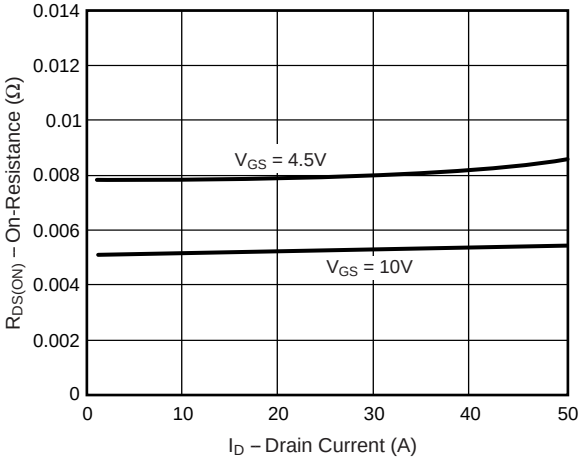
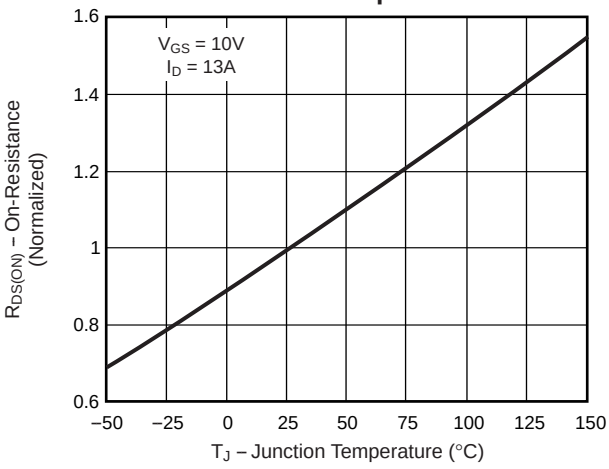


Fig. 5 – On-Resistance vs. Junction Temperature



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Ratings and Characteristic Curves (TA = 25°C unless otherwise noted)

Fig. 6 – On-Resistance vs. Gate-to-Source Voltage

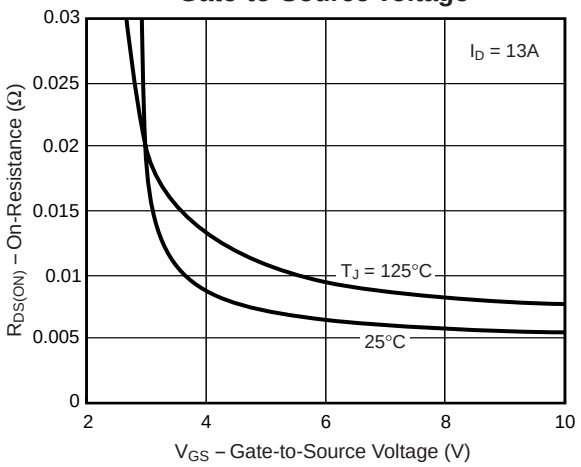


Fig. 7 – Gate Charge

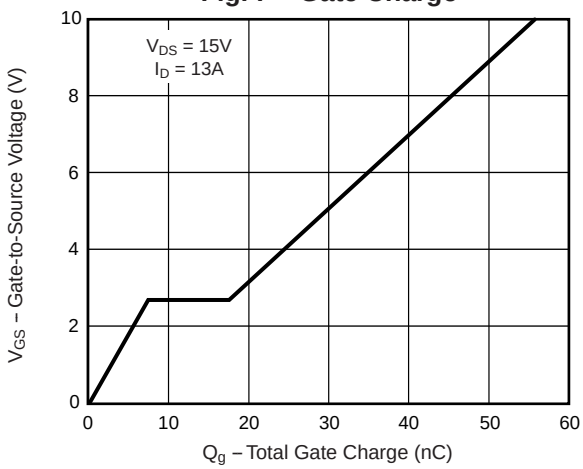


Fig. 8 – Capacitance

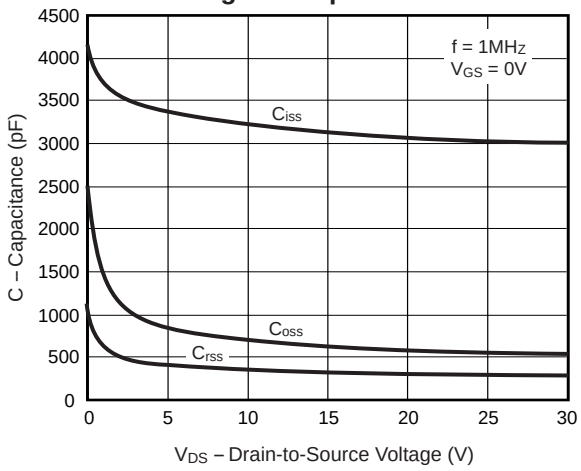
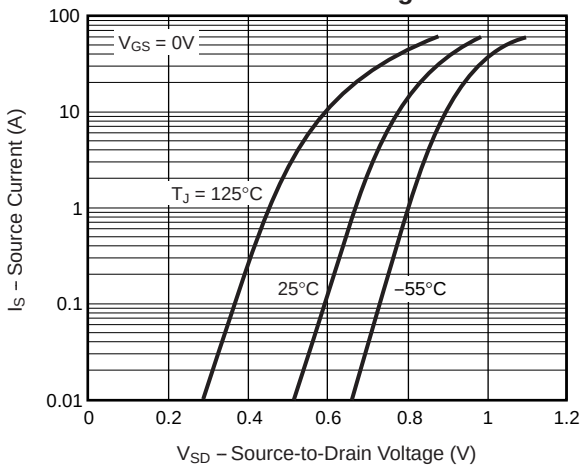


Fig. 9 – Source-Drain Diode Forward Voltage



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Ratings and Characteristic Curves (TA = 25°C unless otherwise noted)

Fig. 10 – Breakdown Voltage vs. Junction Temperature

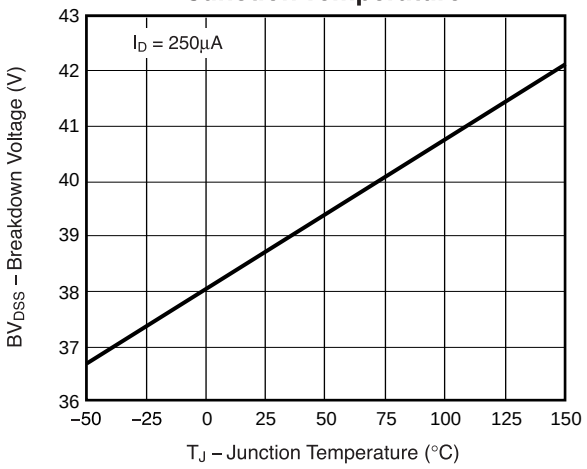

Fig. 11 – Safe Operating Area

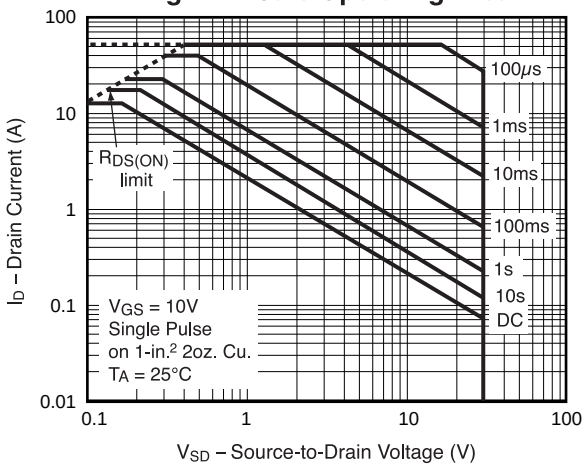

Fig. 12 – Transient Thermal Impedance

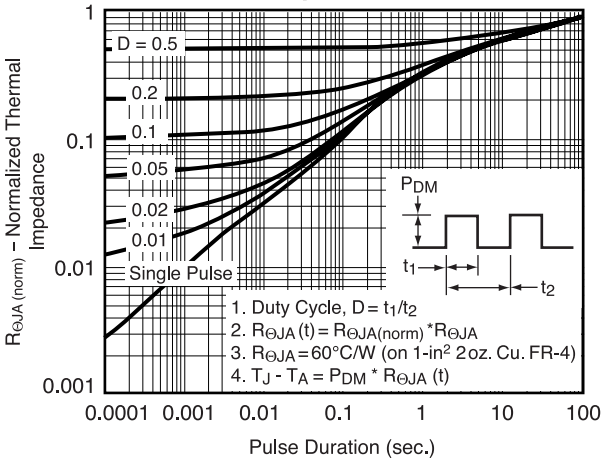

Fig. 13 – Power vs. Pulse Duration